



**INSTITUTO TECNOLÓGICO DE COSTA RICA
ESCUELA DE INGENIERÍA EN ELECTRÓNICA
EL3310: DISEÑO DE SISTEMAS DIGITALES**

TIPO DE ASIGNACIÓN: TRABAJO INDIVIDUAL

**TÍTULO:
“Trabajo Individual #2 -
Bancos de Memoria”**

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**RESPONSABLE TÉCNICO:
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Introducción

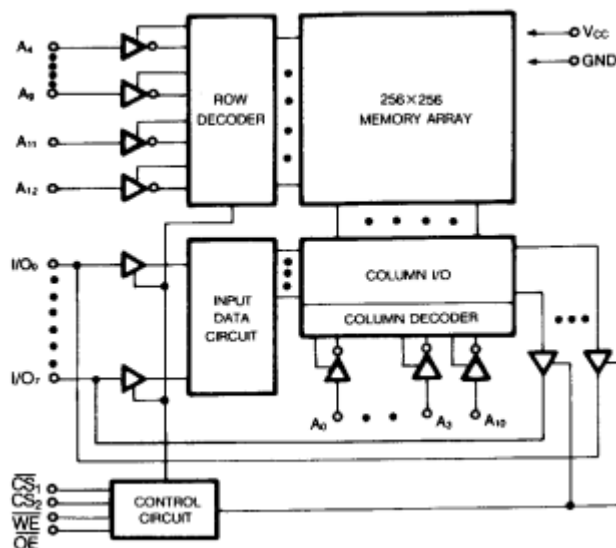
El presente documento corresponde a la Asignación de tipo Trabajo Individual, por parte del curso Diseño de Sistemas Digitales (EL3310) del Instituto Tecnológico de Costa Rica, el mismo pretende dotar al estudiante de capacidades para diseñar bancos de memoria para un microprocesador en particular.

Desarrollo

Utilizando la memoria RAM HY 6264 construya un banco de memoria de 16KX8 bits.

PIN NAMES

A ₀ -A ₁₂	ADDRESS INPUT
I/O ₀ -I/O ₇	DATA INPUT/OUTPUT
CS ₁	CHIP SELECT ONE
CS ₂	CHIP SELECT TWO
WE	WRITE ENABLE
OE	OUTPUT ENABLE
V _{CC}	POWER
GND	GROUND



DC CHARACTERISTICS (V_{CC}=5V±10%, T_A=0°C to 70°C)

SYMBOL	PARAMETER	TEST CONDITIONS	HY6264		UNIT
			MIN.	TYP. ⁽¹⁾ MAX.	
I _{IL}	Input Leakage Current	V _{IN} =GND to V _{CC}	—	—	2 μA
I _{OL}	Output Leakage Current	CS ₁ =V _{CC} , CS ₂ =V _{CC} or OE=V _{CC} , V _{CC} =GND to V _{CC}	—	—	2 μA
I _{CC}	Operating Power Supply Current	CS ₁ =V _{CC} , CS ₂ =V _{CC} , I _{IO} =0mA	—	30	50 mA
I _{CC1}	Average Operating Current	Min. Duty Cycle=100%, CS ₁ =V _{CC} , CS ₂ =V _{CC}	—	40	70 mA
I _{QA}	Standby Power Supply Current	CS ₁ =V _{CC} or CS ₂ =V _{CC}	—	1	3 mA
I _{DD1} ⁽²⁾	Standby Power Supply Current	CS ₁ =V _{CC} =0.2V, CS ₂ =0.2V or ≥V _{CC} =0.2V	L	—	2 300 μA
I _{DD2} ⁽²⁾	Standby Power Supply Current	CS ₁ =0.2V or ≥V _{CC} =0.2V, CS ₂ =0.2V	L	—	2 300 μA
V _{OL}	Output Low Voltage	I _{OL} =2.1mA	—	—	0.4 V
V _{OH}	Output High Voltage	I _{OH} =-1.8mA	2.4	—	V

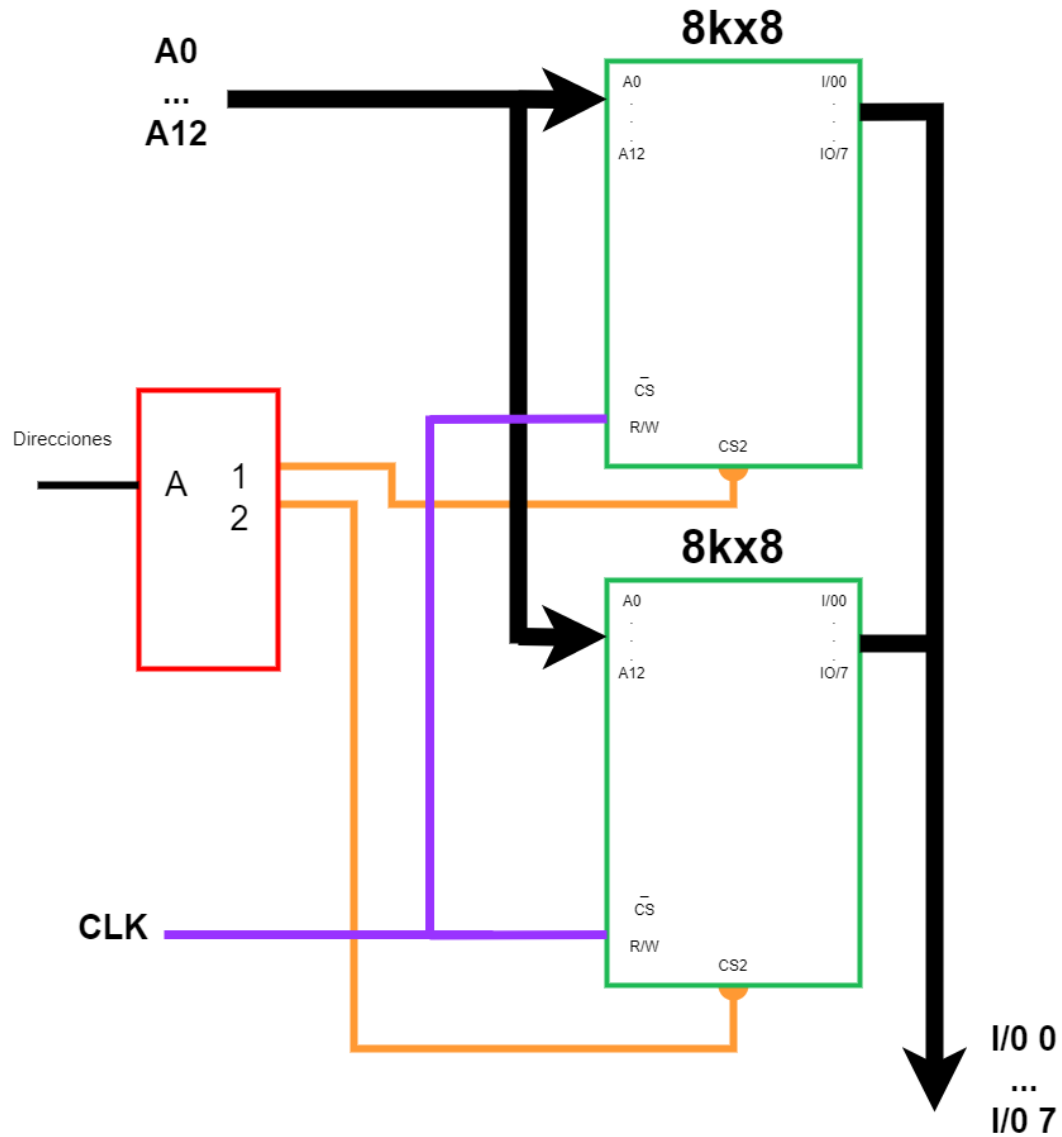
NOTES:
1. Typical value at V_{CC}=5.0V, T_A=25°C and specified loading.
2. V_{IN} only = 0.2V.

AC CHARACTERISTICS (V_{CC}=5V±10%, T_A=0°C to 70°C)

READ CYCLE

SYMBOL	PARAMETER	HY6264-70		HY6264-85		HY6264-10		HY6264-12		HY6264-15		UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
t _{RC}	Read Cycle Time	70	—	85	—	100	—	120	—	150	—	ns
t _{AA}	Address Access Time	—	70	—	85	—	100	—	120	—	150	ns
t _{ACS}	Chip Select Access Time	CS ₁	—	70	—	85	—	100	—	120	—	ns
t _{AS2}	Chip Select Access Time	CS ₂	—	70	—	85	—	100	—	120	—	ns
t _{OE}	Output Enable to Output Valid	—	45	—	50	—	55	—	60	—	70	ns
t _{SL21}	Chip Select to Output in Low-Z	CS ₁	30	—	30	—	30	—	30	—	30	ns
t _{SL22}	Chip Select to Output in Low-Z	CS ₂	10	—	30	—	30	—	30	—	30	ns
t _{OE2}	Output Enable to Output in Low-Z	—	5	—	5	—	5	—	5	—	5	ns
t _{OH21}	Chip Disable to Output in High-Z	CS ₁	0	30	0	35	0	35	0	40	0	30 30 30
t _{OH22}	Chip Disable to Output in High-Z	CS ₂	0	30	0	35	0	35	0	40	0	30 30 30
t _{OH2}	Output Disable to Output in High-Z	—	0	30	0	35	0	35	0	40	0	30 30 30
t _{HA}	Output Hold from Address Change	—	30	—	10	—	10	—	10	—	15	—

Datasheet: <https://datasheetspdf.com/pdf-file/237462/HynixSemiconductor/HY6264-85/1>

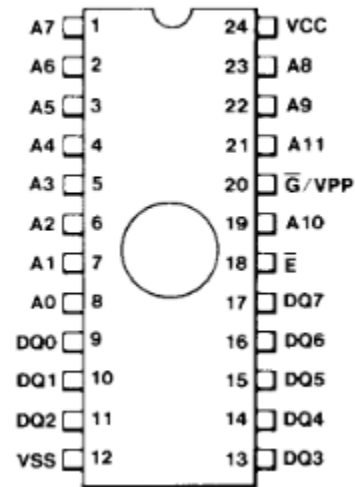


Utilizando la memoria EPROM 2732 construya un banco de memoria de 16KX8 bits.

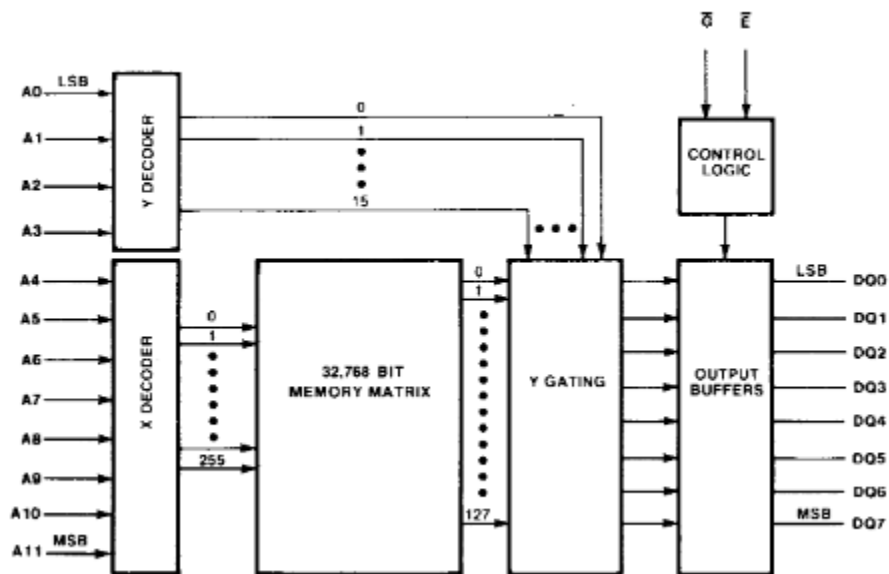
Pin Names

A0-A11	Address Inputs
\overline{E}	Chip Enable (Power Down) Input
\overline{G}/VPP	Output Enable / +25 V Program Input
DQ0-DQ7	Data Output / Programming Inputs
VCC	+5 V Supply
VSS	Ground

Connection Diagram 24-Pin DIP



Block Diagram



Datasheet: <https://pdf1.alldatasheet.com/datasheet-pdf/view/129050/FAIRCHILD/2732.html>

$$2^n = 16(1024) \Rightarrow n = 14 \text{ líneas}$$

